





Date: April/May (TBC)

**Duration:** Half-Day

Venue: Kulim Hi-Tech Park

**Topics:** Fundamentals of Hand Soldering



**Date:** July 15, 2025 (Tuesday)

**Duration:** Half-Day

Venue: (TBC)

Topics: Semiconductor Chip Industry,

Advanced Packaging of Semicondutors



Date: July 17, 2025 (Thursday)

**Duration:** Full-Day

**Venue: SHRDC Auditorium** 

**Topics: First Half** 

PCB Design

Semiconductor Chip

Industry

**Second Half** 

Surface Mount Technology



Date: July 23-24, 2025

**Duration:** Full-Day

**Venue:** Setia Spice Convention Centre

**Topics:** Semiconductor Chip Industry

PCB Design

**Surface Mount Technology** 

Cable & Wire Harness Electronics Assembly

Digitalization of Electronics Manufacturing

**Hand Soldering** 

IPC CONFERENCE & FORUM

## **PENANG**

October 30, 2025 (Thursday) (Tentative)

Advanced Packaging
of Semiconductor:
The Need to Build an
Industrial Eco System



## **PROGRAM SCHEDULE** (Tentative)

9:30 AM • Exhibition Open & Registration/ Networking Tea

Innaugral Session/ Welcome Address by IPC/
Chief Guest Address

11:30 AM • keynote Address

1:00 PM INDUSTRY NETWORKING LUNCH

2:00 PM Panel Discussion

**3:30 PM** • Award Program

**4:30 PM** • Networking & High-Tea

## GLIMPSE OF PAST IPC ACTIVITIES IN MALAYSIA

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## **IPC CONTACT:**

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